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		Application Number	10/671,483
TRANSMITTAL FORM  (to be used for all correspondence after initial filing)		Filing Date	September 29, 2003
		First Named Inventor	Michihiko YANAGISAWA
		Art Unit	1763
		Examiner Name	J. R. Lund
Total Number of Pages in This Submission	5	Attorney Docket Number	506212001200

ENCLOSURES (Check all that apply)						
Fee Transr	mittal Form	Drawing(s)		After Allowance Communication to TC		
Fee /	Attached	Licensing-related Papers		Appeal Communication to Board of Appeals and Interferences		
X Amendmer	nt/Reply	Petition		Appeal Communication to TC (Appeal Notice, Brief, Reply Brief)		
After	Final	Petition to Convert to a Provisional Application	1	Proprietary Information		
Affida	avits/declaration(s)	Power of Attorney, Revocation Change of Correspondence		Status Letter		
Extension	of Time Request	Terminal Disclaimer ,		X Other Enclosure(s) (please Identify below):		
Express At	pandonment Request	Request for Refund		Return Receipt Postcard		
Information	Disclosure Statement	CD, Number of CD(s)				
Certified Control Document(	opy of Priority s)	Landscape Table on	CD			
	issing Parts/ Application	Remarks				
	y to Missing Parts under FR 1.52 or 1.53	·				
SIGNATURE OF APPLICANT, ATTORNEY, OR AGENT						
MORRISON & FOERSTER LLP						
Signature illipation.						
Printed name	Barry E. Bretschneider					
Date	June 7, 2005		Reg. No.	28,055		



## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Examiner: J. R. Lund

Group Art Unit: 1763

In the application of:

Michihiko YANAGISAWA et al.

Serial No.:

10/671,483

Filing Date:

September 29, 2003

For:

MULTI-STEP DRY ETCHING METHOD FOR SOI WAFER

**RESPONSE UNDER 37 CFR 1.111** 

M/S Amendment Commissioner for Patents P.O. Box 1450 Alexandria, Virginia 22313-1450

Sir:

In response to the Action mailed March 9, 2005, please reconsider this application in light of the following Remarks.

## **REMARKS**

Claims 5-17 have been rejected under 35 USC 103(a) as unpatentable over Japanese Patent Application Publication No. Hei. 5-29262 (Nishibe) in view of U.S. Patent No. 6,302,995 (Tanaka) and U.S. Patent No. 6,315,858 (Shinozuka). Applicants respectfully traverse this rejection.

Claim 5 recites a transportation device for taking a silicon on insulator wafer <u>after</u> completion of planarization processing out from the first chamber and transporting the silicon on insulator wafer into the second chamber. Because the claimed etching apparatus has the first vacuum chamber having the small diameter nozzle and the second vacuum chamber